

ABSTRACT

5 A bumped semiconductor component includes bumped contacts, a semiconductor die having die contacts, and a redistribution circuit having conductors for establishing electrical communication between the die contacts and the bumped contacts. The redistribution circuit also includes
10 test contacts in electrical communication with the die contacts and with the bumped contacts. The test contacts allow the die to be tested without electrical engagement of the bumped contacts. The bumped semiconductor component can be contained on a wafer, or can be a singulated component
15 such as a flip chip package. A test system includes the bumped semiconductor component, and an interconnect having contacts configured to electrically engage the test contacts without interference from the bumped contacts. If the test contacts are aligned with the die contacts, the same
20 interconnect can be used to test the bare die as well as the bumped component. A test method includes the steps of: providing the bumped component with test contacts; providing the interconnect with interconnect contacts configured to engage the test contacts without interference from the bumped
25 contacts; and then testing the component by applying test signals through the interconnect contacts to the test contacts.